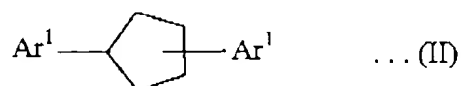
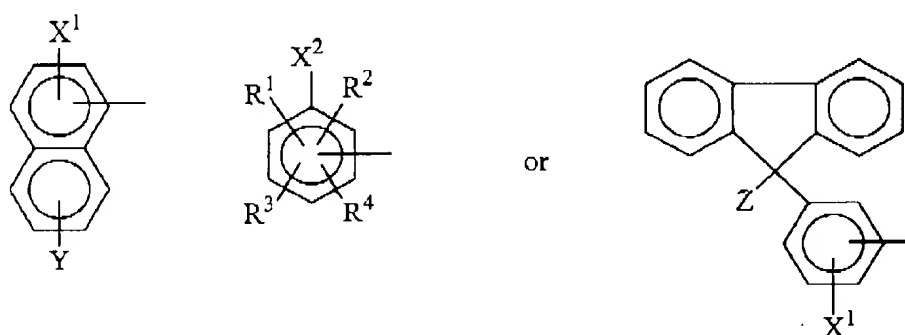


Serial No. 09/986,630

-2-



wherein  $\text{Ar}^1$  represents at least one of monovalent organic groups represented respectively by

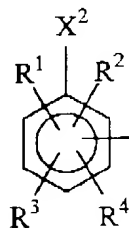


$\text{X}^1$  represents a hydroxyl group or a 2,3-epoxypropoxyl group;  $\text{X}^2$  represents a 2,3-epoxypropoxyl group;  $\text{Y}$  represents a hydrogen atom, a hydroxyl group or a 2,3-epoxypropoxyl group;  $\text{Z}$  represents a hydrogen atom, a phenyl group, a hydroxyphenyl group or a 2,3-epoxypropoxyphenyl group; and  $\text{R}^1$  to  $\text{R}^4$  are each a group selected independently from a hydrogen atom, an alkyl group and an aryl group having 1 to 10 carbon atoms and a halogen atom;

in a case where both  $\text{Ar}^1$ 's are

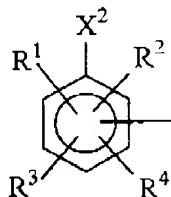
Serial No. 09/986,630

-3-

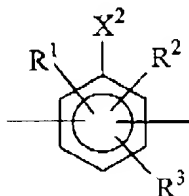


, the Ar<sup>1</sup>'s are bonded respectively to 1 and 3 positions of the cyclopentane ring of formula (II).

16. (Amended) The compound according to claim 1, wherein the Ar<sup>1</sup> is a monovalent organic group represented by



and the Ar<sup>2</sup> is a divalent organic group represented by

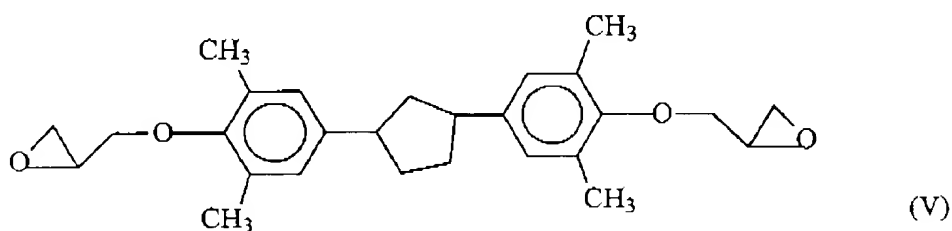


Serial No. 09/986,630

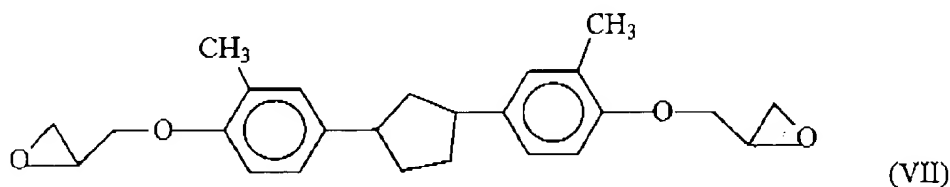
-4-

wherein  $X^2$  represents a 2,3-epoxypropoxyl group;  $R^1$  to  $R^4$  are each a group selected independently from the group consisting of a hydrogen atom, an alkyl group and an aryl group having 1 to 10 carbon atoms and a halogen atom.

24. (Amended) A compound according to claim 23 having the formula (V)



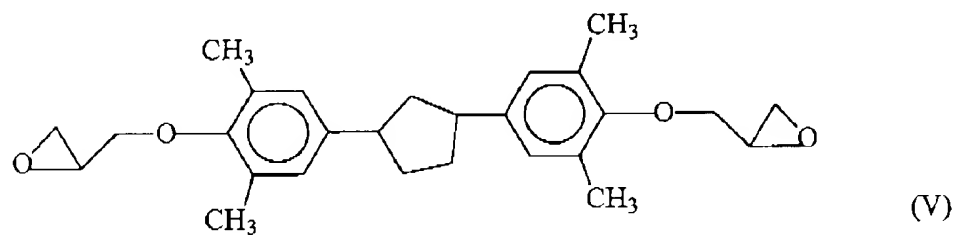
25. (Amended) A compound according to claim 23 having the formula (VII)



27. (Amended) An epoxy resin molding material according to claim 26 including a compound represented by formula (V)

Serial No. 09/986,630

-5-



28. (Amended) An epoxy resin molding material according to claim 26 including a compound having the formula (VII)

